NEW PRODUCT

NP560 Solder Paste

THE ULTRA LOW VOIDING PASTE UNDER QFNS

NP560 IS A NO-CLEAN, LEAD-FREE HALOGEN-FREE, SOLDER PASTE FEATURING:

- Ultra low voiding performance under QFNs
- Wide reflow profile window with good solderability on various PCB surface finish
- Excellent solderability across varied profiles in both air and nitrogen
- Consistent printing performance to 0.50 and 0.5 AR
- Excellent activity and printability
- Very low solder balling and graping
- Extremely stable paste properties
- Colorless residues for ease post-reflow inspection
- Halide and halogen-free

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